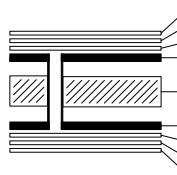


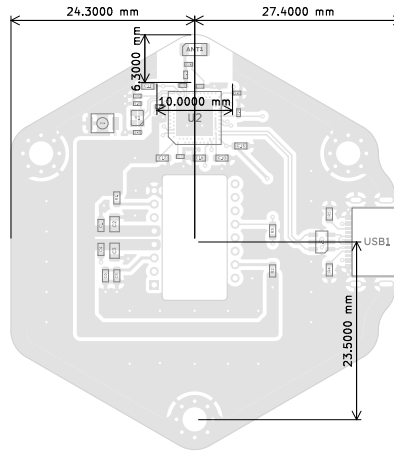
HexTrack PCB Fabrication Document

Top Fabrication (Scale 1:1)



Material	Layer	Thickness	Material	Type
	F.Paste			Paste Mask
	F.Silkscreen			Silkscreen
	F.Mask	0.01 mm	Solder Resist	Solder Mask
Copper	F.Cu	0.035 mm (1 oz)		Signal
Core		1.51 mm	FR4	Dielectric
Copper	B.Cu	0.035 mm (1 oz)		Signal
	B.Mask	0.01 mm	Solder Resist	Solder Mask
	B.Silkscreen			Silkscreen
	B.Paste			Paste Mask

Total thickness: 1.6 mm

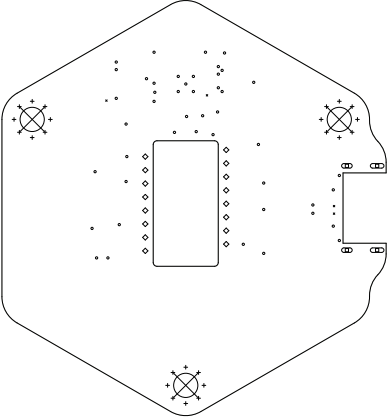


Board Name	Project Name	Engineer	Filename	Date	Version	Page Size
HexTrack PCB	HexTrack	TMShader	hextrack.kicad_pcb	2025-01-09	v0.0.1	A4

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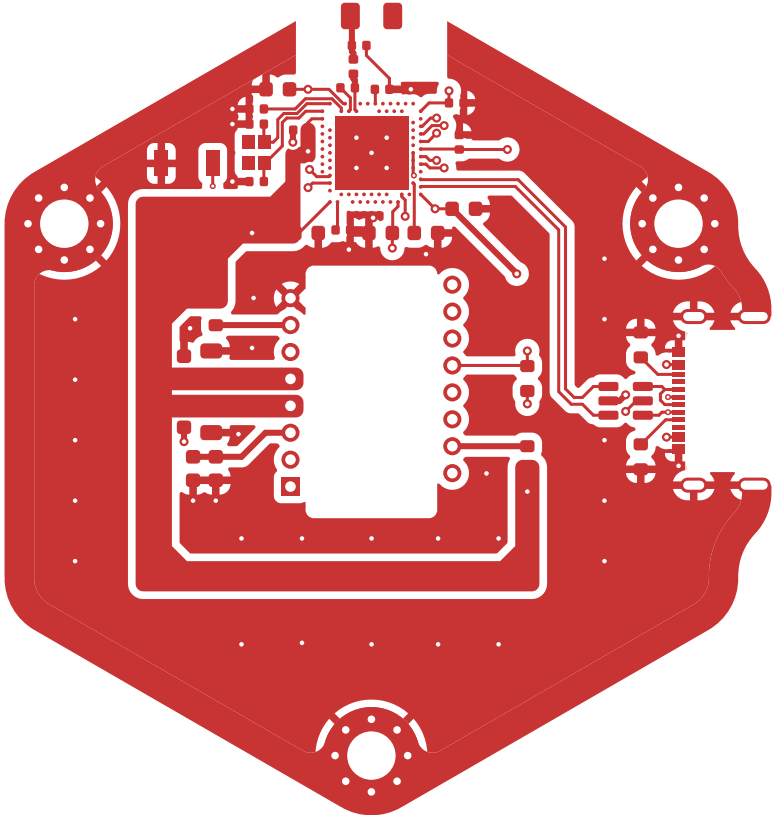
Drill Map (Top view) (Scale 1:1)

Symbol	Count	Hole Size
⊗	3	3.20 mm
□	4	0.60 mm
·	4	0.20 mm
◇	16	0.70 mm
+	24	0.50 mm
°	46	0.30 mm



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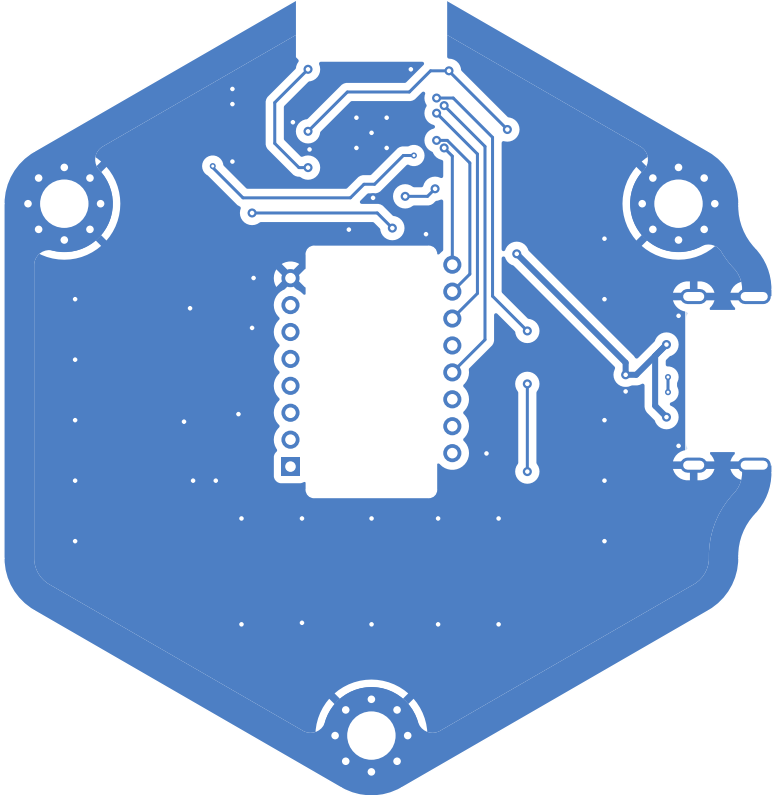
F.Cu (SIG/GND)



Board Name	Project Name	Engineer	Filename	Date	Version	Page Size
HexTrack PCB	HexTrack	TMShader	hextrack.kicad_pcb	2025-01-09	v0.0.1	A4

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B.Cu (SIG/GND)



Board Name	Project Name	Engineer	Filename	Date	Version	Page Size
HexTrack PCB	HexTrack	TMShader	hextrack.kicad_pcb	2025-01-09	v0.0.1	A4